

Search

[PRODUCTS](#) [APPLICATIONS](#) [DESIGN SUPPORT](#) [SAMPLE AND BUY](#) [ABOUT US](#) [CONTACT US](#) [MYMICROCHIP LOGIN](#) [more...](#)

Product Change Notification - KSRA-27FAPU261 [\(Printer Friendly\)](#)

Date:

19 Feb 2018

Product Category:

Capacitive Touch Sensors; Touch Controllers; 8-bit PIC Microcontrollers

Notification subject:

CCB 3042 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN package at NSEB assembly site

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 200K wafer technology available in 8L DFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach material, G770HCD or G700LTD molding compound material and EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach material, G700LTD molding compound material and C194 lead frame material

Pre and Post Change Summary:

	Pre Change	Post Change
--	------------	-------------

Assembly Site	UTAC Thai Limited LTD. (NSEB)		UTAC Thai Limited LTD. (NSEB)
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	EFTEC-64T		C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 19, 2018 (date code: 1812)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts

Time Table Summary:

Workweek	August 2017					-- >	February 2018				March 2018				
	31	32	33	34	35		05	06	07	08	09	10	11	12	13
Initial PCN Issue Date	X														
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date													X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

August 02, 2017: Issued initial notification.

August 31, 2017: Re-issued initial notification to include CCB 3074.

February 19, 2018: Issued final notification. Attached the Qualification Report. Update subject to remove CCB 3074. Revised the affected parts list. Provided estimated first ship date on March 19, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-27FAPU261_Affected CPN.pdf](#)

[PCN_KSRA-27FAPU261_Qual Report.pdf](#)

[PCN_KSRA-27FAPU261_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."



[Products](#) | [Applications](#) | [Design Support](#) | [Training](#) | [Sample And Buy](#) | [About Us](#) | [Contact Us](#) | [Legal](#) | [Investors](#) | [Careers](#) | [Support](#)

©Copyright 1998-2018 Microchip Technology Inc. All rights reserved.